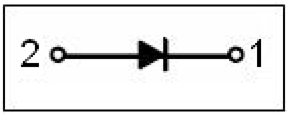
修订记录 / Revised record

描述 / Descriptions

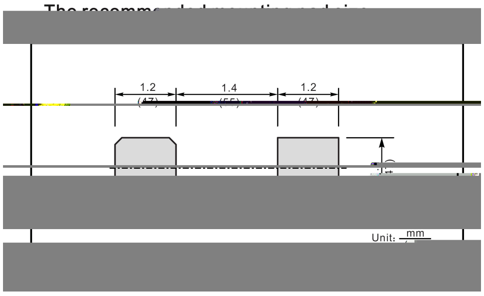
特征 / Features

用途 / Applications

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



放大及印章代码 / h_{FE} Classifications & Marking

极限参数 / Absolute Maximum Ratings(Ta=25℃)

			℃
			℃

电性能参数 / Electrical Characteristics(Ta=25℃)

电参数曲线图　/　Electrical Characteristic Curve

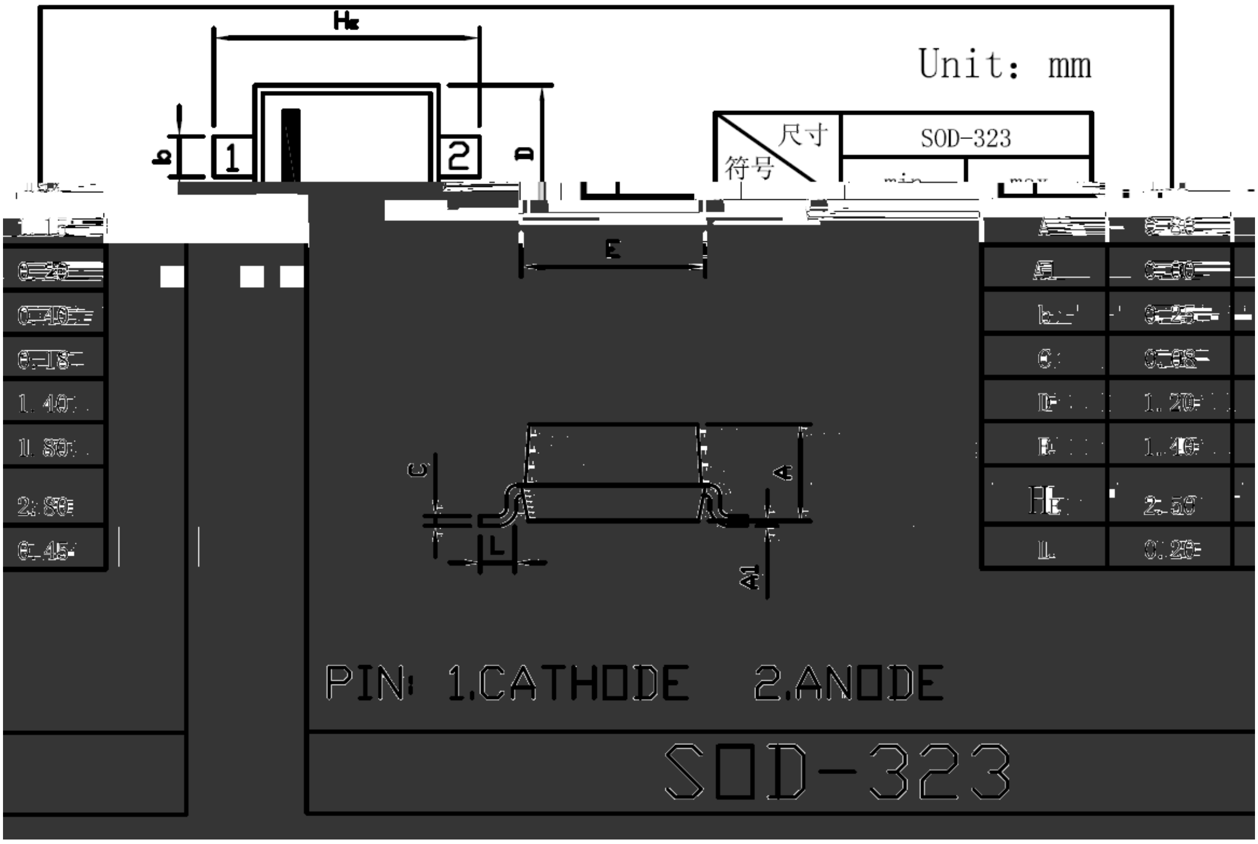
Fig.1 Derating curve

Fig.2 Typical Reverse Characteristics

Fig.3 TYPICAL FORWARD VOLTAGE

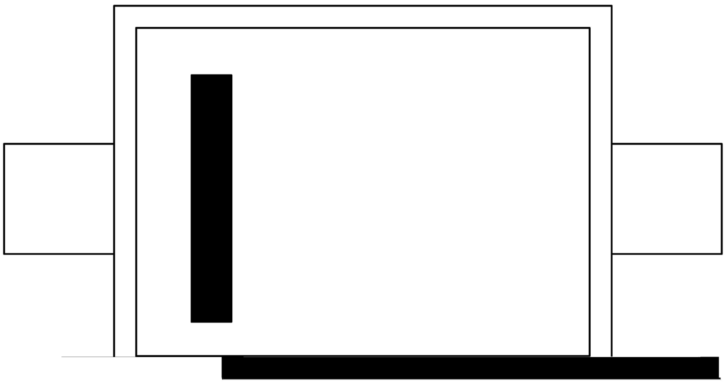
Fig.4 Typical Junction Capacitance

外形尺寸图 / Package Dimensions

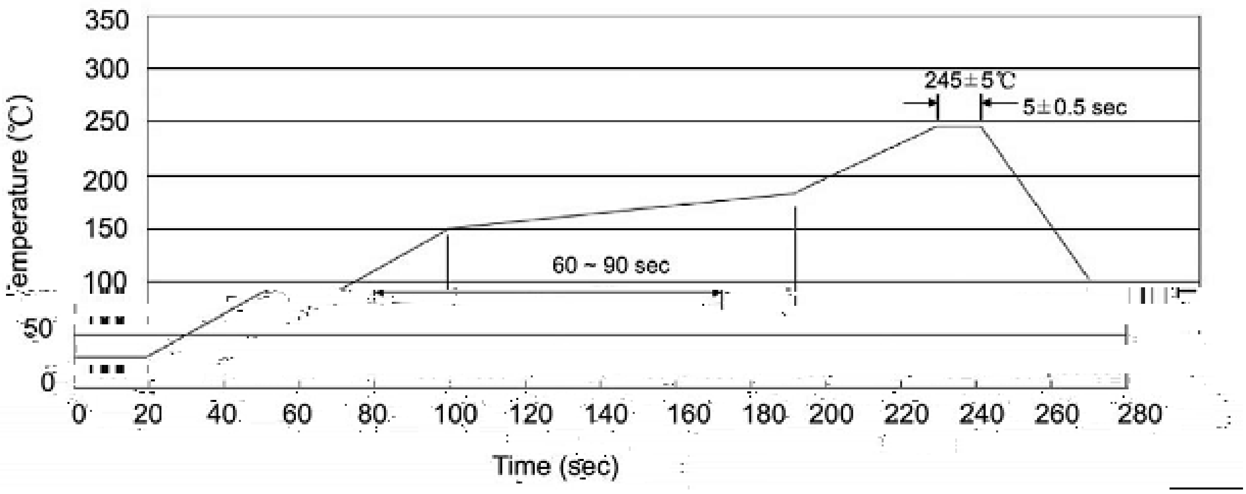


尺寸 符号	SOD-323 min	SOD-323 max
A	0.80	1.15
A1	0.00	0.20
b	0.25	0.40
c	0.08	0.18
D	1.20	1.40
E	1.60	1.80
HE	2.50	2.80
L	0.20	0.45

印章说明 / Marking Instructions



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

、预热温度 ~ ℃，时间 ~ ℃

、峰值温度 ± ℃，时间持续为 ± ± ℃ ±

、焊接制程冷却速度为 ~ ℃ ℃

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度： ± ℃ 时间： ± ± ℃ ±

包装规格 / Packaging SPEC.

卷盘包装

	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-323	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

使用说明 / Notices